

### **ABSTRACT OF THE DISCLOSURE**

Embodiments provide a method, article of manufacture, and apparatus for providing an component package. In one embodiment, a cover assembly including a plurality of air-cavity covers is bonded to a carrier having a plurality of components thereon. Each air-cavity cover encapsulates at least one of the components to form a multi-component assembly. Subsequently, the multi-component assembly is then separated into individually packaged component devices.